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For

METHOD AND APPARATUS FOR FRODUCING MOLD

PCT International Application No.: PCT/JP01/03896

POT International Filing Date: May 10, 2001

U.S. Application No.

(if known, see 37 CFR 1.5): 10/009 903

Atty. Docket No.: Ace Case 6

Box PCT

Assistant Commissioner for Patents Washington, DC 20231

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Sir:

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390.9912

APR 0 1 2002 TC 1700